

SOT2052-1

LFBGA485, low profile fine pitch ball grid array package, 485 terminals, 0.5 mm pitch, 15 mm x 15 mm x 1.38 mm body

10 March 2020

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA485
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Mounting method type	S (surface mount)
Issue date	17-02-2020
Manufacturer package code	98ASA01525D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	14.85	15	15.15	mm
package width	14.85	15	15.15	mm
package height	-	1.38	1.52	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	485	-	



2 Package outline

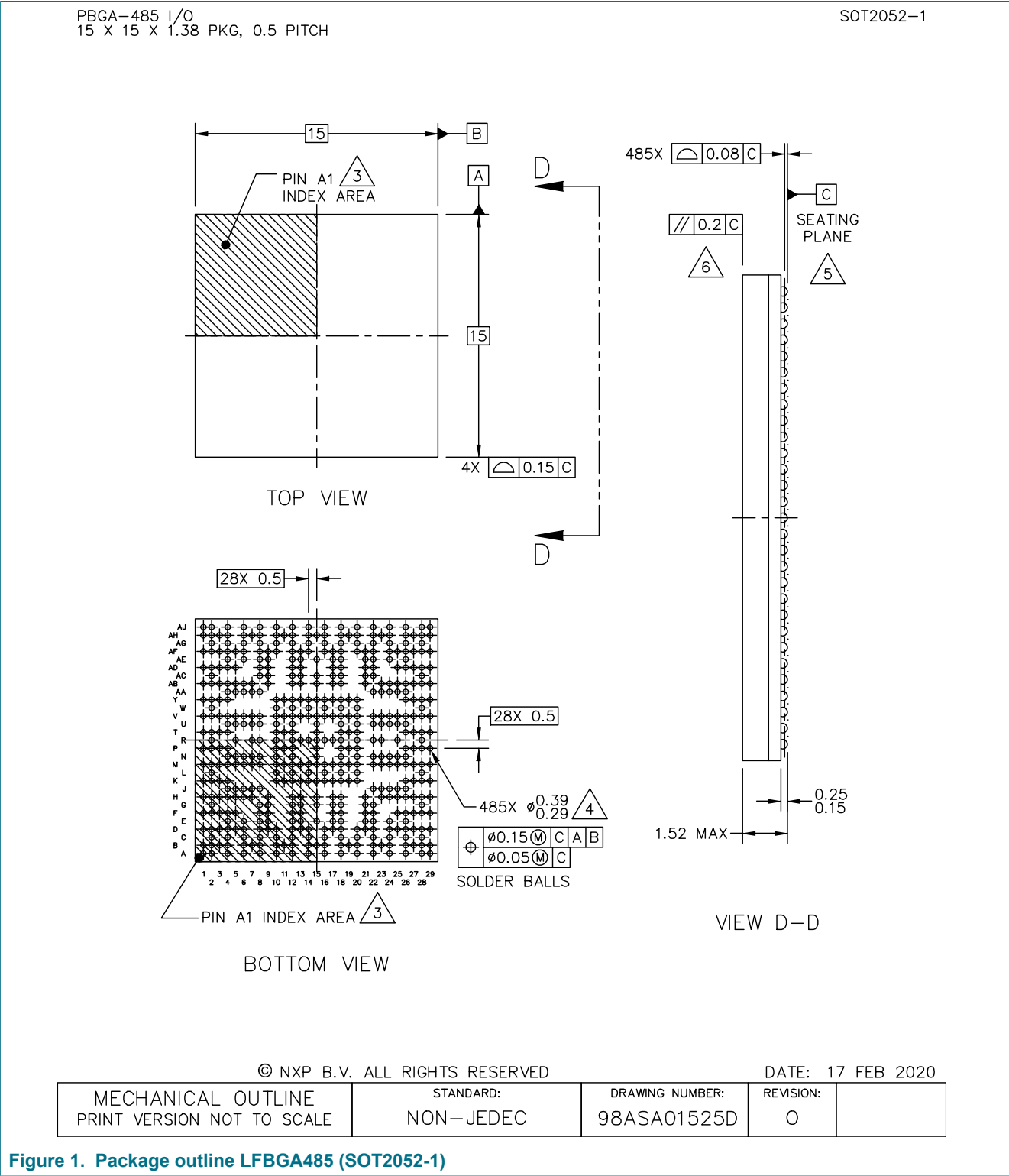
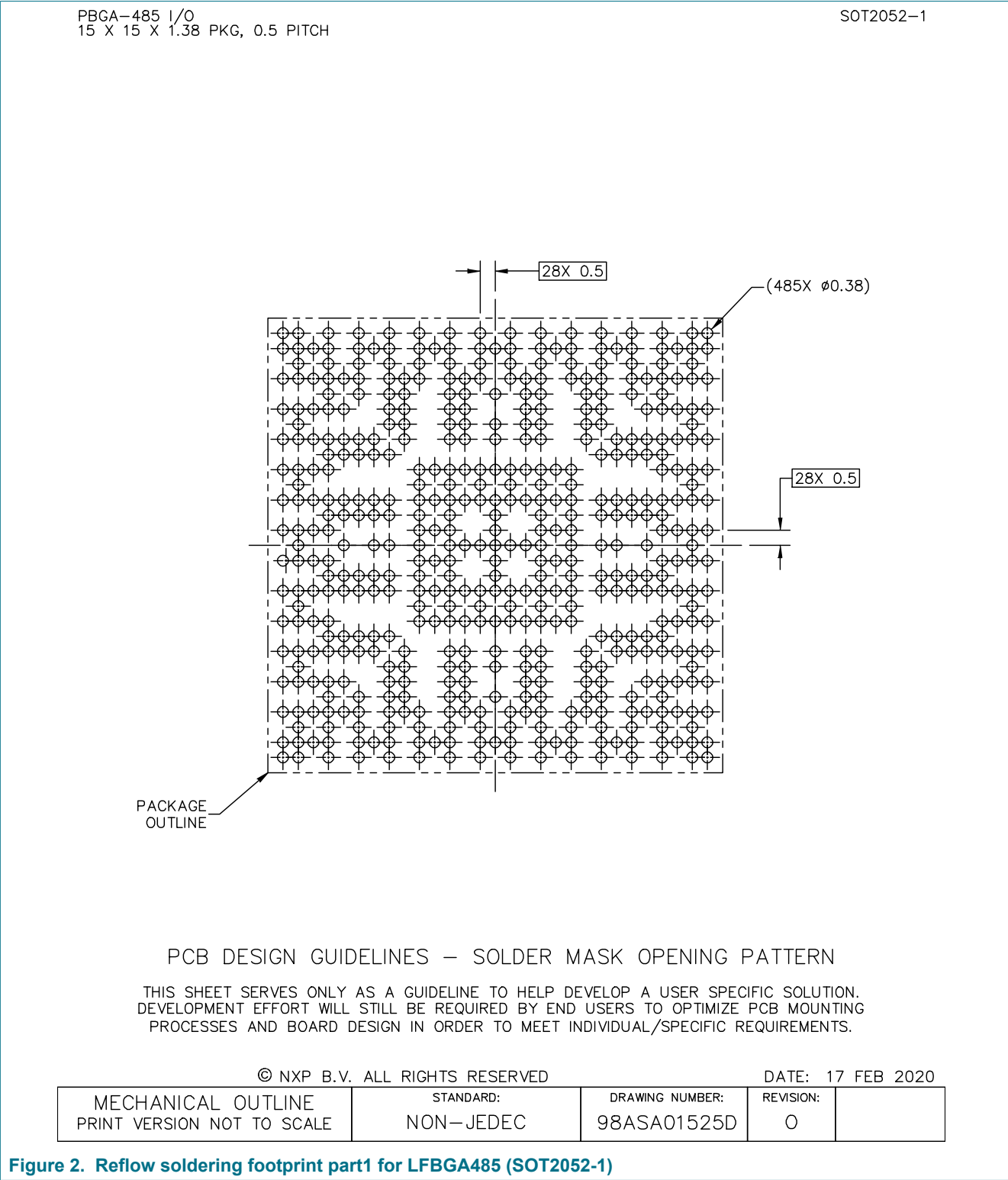


Figure 1. Package outline LFBGA485 (SOT2052-1)

LFBGA485, low profile fine pitch ball grid array package, 485 terminals, 0.5 mm pitch, 15 mm x 15 mm x 1.38 mm body

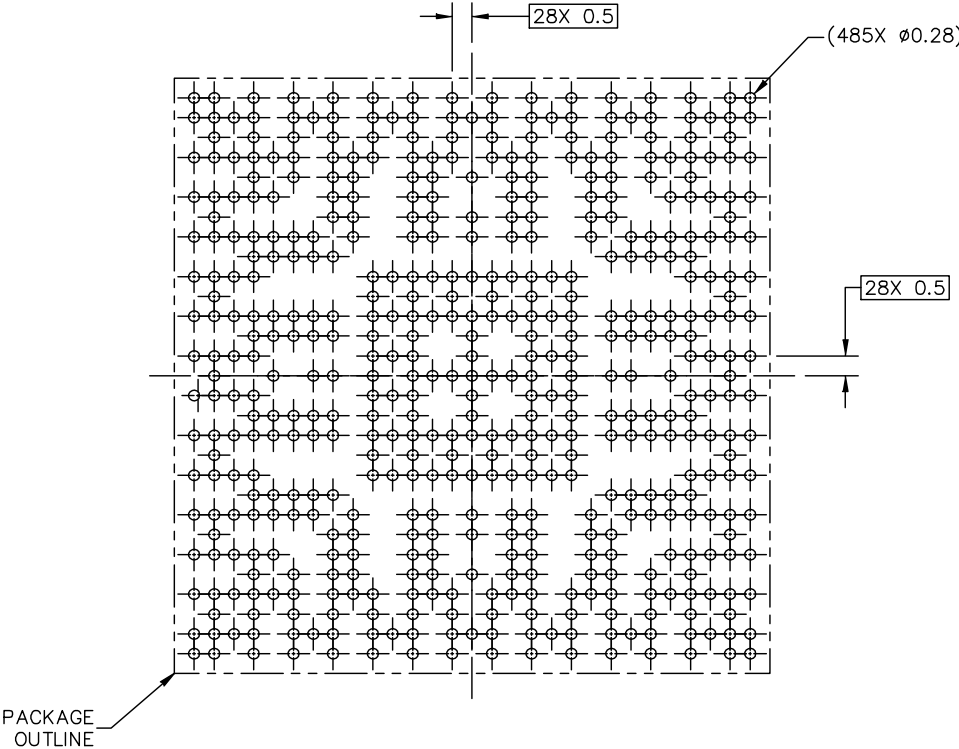
3 Soldering



LFBGA485, low profile fine pitch ball grid array package, 485 terminals, 0.5 mm pitch, 15 mm x 15 mm x 1.38 mm body

PBGA-485 I/O
15 X 15 X 1.38 PKG, 0.5 PITCH

SOT2052-1



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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DATE: 17 FEB 2020

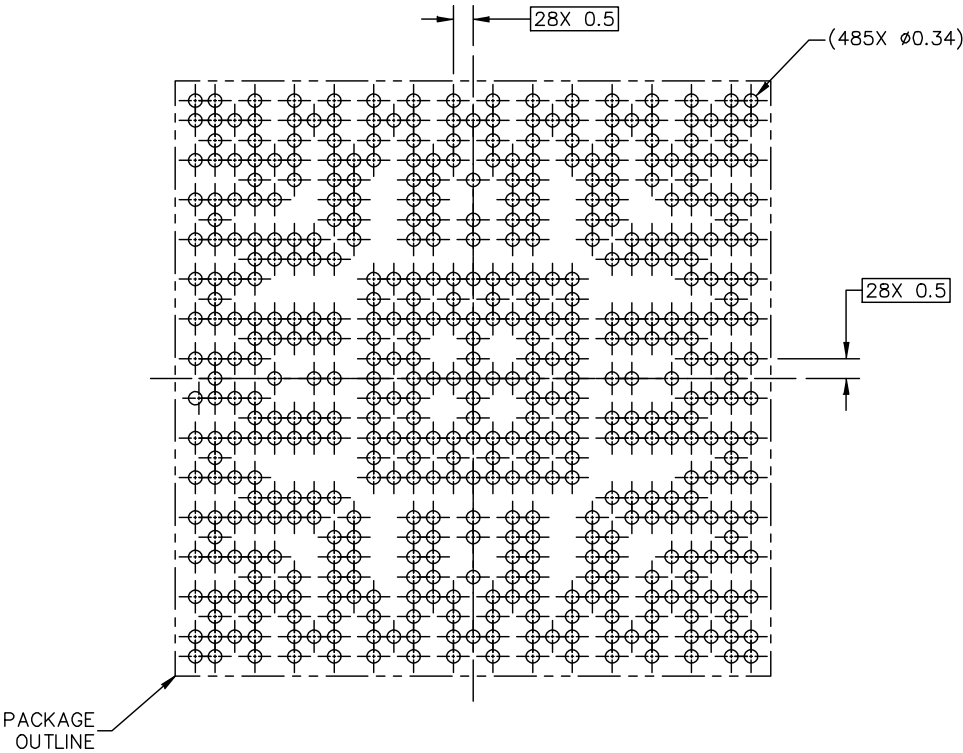
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01525D	REVISION: 0	
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Figure 3. Reflow soldering footprint part2 for LFBGA485 (SOT2052-1)

LFBGA485, low profile fine pitch ball grid array package, 485 terminals, 0.5 mm pitch, 15 mm x 15 mm x 1.38 mm body

PBGA-485 I/O
15 X 15 X 1.38 PKG, 0.5 PITCH

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RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 4. Reflow soldering footprint part3 for LFBGA485 (SOT2052-1)

LFBGA485, low profile fine pitch ball grid array package, 485 terminals, 0.5 mm pitch, 15 mm x 15 mm x 1.38 mm body

PBGA-485 I/O
15 X 15 X 1.38 PKG, 0.5 PITCH

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NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
- 4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
- 5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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Figure 5. Package outline note LFBGA485 (SOT2052-1)

4 Legal information

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